

CHIP PACKAGE WITH DIE AND SUBSTRATE

Appl. No. : 10/055,568 Confirmation No. 6093
Applicant : Mou-Shiung Lin,
Jin-Yuan Lee,
Ching-Cheng Huang
Filed : January 22, 2002
TC/A.U. : 2813
Examiner : Mitchell, James M
Docket No. : MEGP0004USA
Customer No. : 27765

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

RESPONSE TO NON-FINAL OFFICE ACTION

5 Sir:

The Non-Final Office Action mailed Oct. 31, 2008 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

10 **Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 7 of this paper.